

June 2020

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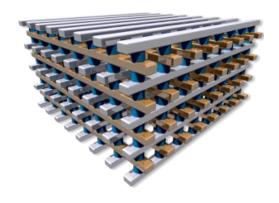
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COMPANY HIGHLIGHTS.



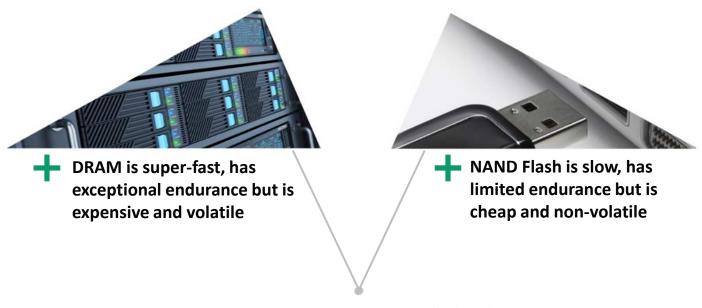


- **World-leading** Silicon Valley based Interface Switching ReRAM developer
- Completed Additional Wafers Lot of 300mm wafers, most successful to date
- **Demonstrated record improvement in speed and endurance**
- 4DS is the most advanced Interface Switching ReRAM
- The most promising Interface Switching ReRAM cell for Storage Class Memory
- Joint development agreement with Western Digital subsidiary HGST since 2014
- Strategic collaboration with imec signed in November 2017
- 23 granted US patents wholly owned and 9 pending or filed
- Completed A\$4.5 mil placement, launched A\$2.5 k SPP mil

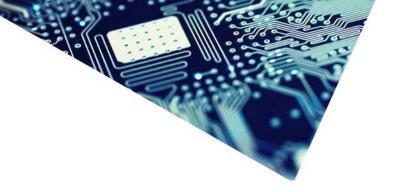
THE CHALLENGE.

DRAM and NAND Flash are the main technologies utilized today.

Both are US\$95-56 billion annual markets - and growing.



A new innovation is needed and the industry refers to it as Storage **Class Memory** - over time this is predicted to have a market size as large as DRAM and NAND Flash



STORAGE CLASS MEMORY.

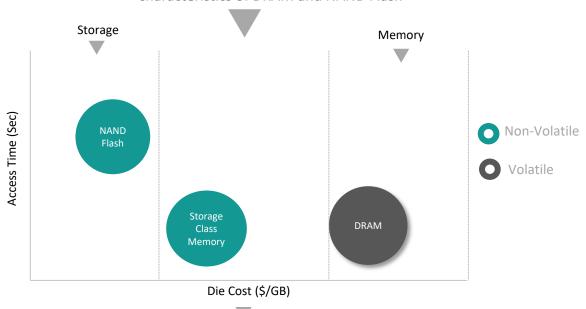
Storage Class Memory is emerging as the leading new category to extend the memory hierarchy.

4DS Interface Switching ReRAM will not be a "me too" technology in the embedded and NAND Flash sectors.

Interface Switching ReRAM is a unique ReRAM being developed specifically for Storage Class Memory applications.

STORAGE CLASS MEMORY

Attempts to combine the best characteristics of DRAM and NAND Flash



Battleground for next generation memory technology.

Faster – DRAM-like read speed **Cheaper** – NAND Flash-like costs Non-volatile – Retains data when power is off

BEST DATA SET RECORDED BY 4DS.

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4DS Interface Switching ReRAM has now shown record achievements in relevant Storage Class Memory categories

- Best endurance data recorded two to three times better than previously reported
- Highest recorded speed near DRAM speed an area-based ReRAM first US patents now granted
- No need for speed crippling error correction <u>a ReRAM first US patents now granted</u>
- Retention data recorded additional studies to be completed to assess upper limits
- Data validated by two of the worlds leading semiconductor participants imec / HGST

SEVEN YEAR PARTNERSHIP WITH HGST.

HGST, is a subsidiary of Western Digital Corporation (US\$13.5 billion market cap), one of the largest global leaders in digital storage

- Strategic innovator in emerging high growth technologies
- Commenced JDA in 2014 Renewed in 2015, 2016, 2017, 2018, 2019 and 2020
- Insight into what is important in a data-centric world
- Now actively involved with 4DS / imec and remain committed to Storage Class Memory
- Siva Sivaram, President of Technology and Strategy at Western Digital, commented "We are committed to ReRAM, it is scalable with greater density, lower cost and latency and longer endurance"*



unec **WORLD # 1 AND 4DS PARTNER.**

imec, is the world's #1 independent semiconductor development institute

- Collaborates with the who's who of electronic products and systems
- Collaborates with makers of high-volume high-density memories
- Has a world leading track record in the transfer of semiconductor processes
- Uses the same tools as industry for high-volume production of high-density memories
- Has a proven megabit memory platform to fast track development of megabit chip
- Used this platform to explore a wide range of emerging memories



unec COLLABORATION OBJECTIVES.

- imec and 4DS completed Additional Wafers Lot manufacturing after discussions and input from Western Digital
- Complete discussions with imec and HGST in July 2020 regarding next steps to incorporate new technical developments established from first megabit platform and additional wafers iterations
- Develop a fully transferable fabrication compatible process
- Mimic industry standard high volume production
- Utilizing imec's proven megabit memory platform reduces time and cost
- End goal is to fabricate a megabit 4DS Interface Switching chip with a fully functioning Storage Class Memory

BOARD AND MANAGEMENT.

Global expertise founding and building high-tech companies.



JIM DORRIAN

Non-Executive Chairman

- Served as CEO of several Silicon Valley companies
- Extensive M&A experience
- Partner at VC firm Crosspoint Venture Partners



Dr GUIDO ARNOUT

CEO & Managing Director

- 30+ years in commercialising electronics technology
- Successes include, Power-Escape, CoWare, CrossCheck Technology and Silvar-Liso



HOWARD DIGBY

Non-Executive Director

- Former senior roles at IBM, Adobe, Gartner and the Economist Group
- Director of Vortif Ltd, Cirralto Ltd, Elisight Ltd and Hearmeout Ltd
- Advisor to a number of early stage technology companies



Dr SESHUBABU DESU

Chief Technology Officer

- Expert in thin films, semiconductor processing and non-volatile memories
- Professor, Dean and Head of Electrical Engineering at various universities



DAVID McAULIFFE

Executive Director

- Experienced company director
- Involved in numerous capital raisings and in-licensing of technologies
- Founder of several companies in Australia, France and the UK, many of which are now ASX listed. The most recent was Invex Therapeutics Ltd



MICHAEL VAN BUSKIRK

Chief Engineering Officer

- Executive roles with a number of leading memory companies in Silicon Valley
- These include, Adesto Technologies Corporation, Innovative Silicon Inc and Spansion Inc.

PLACEMENT AND SHARE PURCHASE PLAN (SPP).

Completed a A\$ 4.5 million placement at A\$0.045 per share to USA and Australian institutions and high net worth investors

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- Placement was extremely well supported
- Undertaking a SPP for A\$ 2.5 million at the same price as the placement for up to A\$15,000
- The Company may take oversubscriptions or place any shortfall from SPP
- SPP Booklet will be sent to eligible shareholders as soon as possible
- Upon successful completion the cash position will be circ A\$ 9.25 mil*

^{*} Assumes SPP fully subscribed and less placement fees

USE OF PROCEEDS

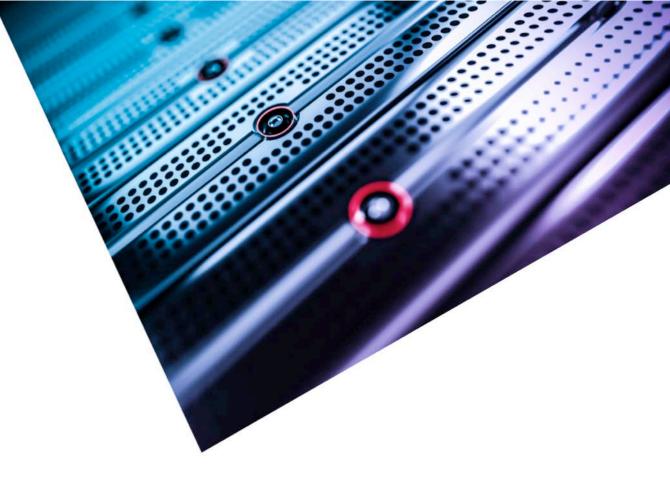
- Fast track the manufacture of a megabit chip with imec and Western Digital / HGST
- File additional patents and maintain existing 23 granted patents
- General working capital



CAPITAL STRUCTURE.

ASX Code	4DS
Market Cap (Fully Diluted)	A\$ 64 Million*
Ordinary Shares on Issue	1,296 Million*
Unlisted Options	129 Million
Cash	~A\$9.25 Million – July 2020**
Board and Management	6.1%***

^{*}As at 29 June 2020 placement price and assumes successful SPP



^{**}Assumes successful SPP and after placement expenses

^{***} Assumes successful SPP

VALUE PROPOSITION.

- 4DS is developing a **breakthrough Interface Switching ReRAM Storage Class Memory solution**
- Recently produced pivotal data applicable for Storage Class Memory and best to date
- Seven year strategic partnership with HGST, leader in digital storage
- → Imec strategic collaboration to develop megabit chip with the world # 1 developer in nano electronics
- Strong patent portfolio with 23 granted patents wholly owned and developed in-house
- **World-class team** of memory specialists, material scientists and test engineers
- Board experienced in founding, building and exiting high tech companies
- Sufficient cash to meet current objectives



TIMETABLE*.

Record Date for SPP

Booklet Despatch and Opening of SPP

- Settlement of Placement

Allotment of Placement Shares

Trading of Placement Shares on ASX

Closing date of SPP

Issue Date of SPP Shares

Friday, 26 June 2020

Friday, 3 July 2020

Friday, 3 July 2020

Monday, 6 July 2020

Monday 6 July 2020

Friday, 24 July 2020

Wednesday, 30 July 2020

^{*}Indicative and the Company reserves the right to close the SPP early

